ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	PC, Bannockl	burn, Illinois. A	ll rights reserved ations.	under both	This docume level parts, t	ent is a declarat he declaration e	ion of the su	ibstances s all lower	within the manufacture level materials for w	urer listed which the u	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi									2024-05	2024-05-07				
ntact Name Title - Contact					Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards Product Enviro Con			o Compliance		NA			Produ	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative			entative	tive I		Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	sion Manufacturing Site			Weight*	UOM	Unit Type	
	LC8981	C898124EP3XC-MH OIS&AF Driver				2024-05-07 PI		РНМ		6.98	mg	Each		
Anufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	Array Material Terminal Base Alloy		J-STD-020 MSL	Rating	Peak Process Body		dy Temperature Max Time at Peak		k Tempera	ture Num	ber of Reflow Cyd	eles		
SnAgCu CU Alloy			1		260		С	30	seco	nds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Backside Protection Film	0.32	mg	Supplier	Epoxy Resin	25068-38-6		0.0608	mg	
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.192	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0032	mg	
			Supplier	Acrylic resins	Proprietary Data		0.064	mg	
Die	5.78	mg	Supplier	Silicon (Si)	7440-21-3		5.78	mg	
Electrode	0.23	mg	Supplier	Copper (Cu)	7440-50-8		0.23	mg	
Protection coat	0.25	mg	Supplier	Epoxy resins	129915-35-1		0.25	mg	
Solder Ball	0.4	mg	Supplier	Silver (Ag)	7440-22-4		0.012	mg	
			Supplier	Tin (Sn)	7440-31-5		0.386	mg	
			Supplier	Copper (Cu)	7440-50-8		0.002	mg	